www.ametekaegis.com

AMETEK®
ENGINEERED INTERCONNECT AND PACKAGING

Infrared Packages, Headers and Dewar Assemblies

AMETEK ECP designs and manufactures a wide range of **infrared packages, headers and Dewar assemblies** using HTCC and GTMS technologies for various military and commercial applications.

KEY FEATURES

- In-house package and Dewar design
- Circuit routing
- Uncooled cavity packages
- Tombstone-type feedthroughs
- Circular headers
- Hermeticity to 1 x 10^{-13} STD CC He/sec
- Shortest time to market
- Superior design system
- Lowest package development cost
- In-house tooling
- Ceramic green wafer tooling
- Braze integration tooling
- Leveraged process support
- Precision laser machining (ceramic)
- Precision diamond dicing (ceramic)
- Selective masking and plating
- Electron beam welding (coldfingers)
- Vacuum brazing (Titanium)
- Production capability
- Leveraged capacity support



NOTE:

GTMS technology (matched seals, not compression seals) meets the same hermeticity standard as HTCC. GTMS is more cost effective.

However, the GTMS solution is not as mechanically robust when exposed to mechanical shock, gunfire shock, and vibration.

AEGIS™ / AMETEK ENGINEERED INTERCONNECT AND PACKAGING

E: aegis.info@ametek.com
T: +1 508 998 3141

GSP GLASSEAL PRODUCTS™ / AMETEK ENGINEERED INTERCONNECT AND PACKAGING

E: Aem.info@ametek.com
T: +60 46 433 062

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